



Call for Papers

ICPT

October 25 – 27, 2007
Hilton Hotel, Dresden, Germany

www.icpt2007.com

Conference Objective

Over the last 15 years, Chemical Mechanical Polishing (CMP) has developed into one of the key technologies in the ULSI fabrication process. It can be viewed as an enabling technology for manufacturing state-of-the-art microprocessors, high-density memories and other advanced microelectronic circuits. Without CMP, accurate printing of nanometer chip structures is impossible. CMP has helped to introduce multilevel interconnection and the employment of copper metallization. Emerging CMP applications include MEMS and nanotechnology, but advancements in CMP also stimulate related areas like wafer polishing and production of optical surfaces. In order to keep pace with future ULSI developments, improved Chemical Mechanical Polishing processes have to be available for FEOL and BEOL applications. For reasons of productivity enhancement, tool reliability improvements, cost reductions, process automation and advanced process control are required. Finally, new fields of applications for CMP, which certainly exist plentiful, have to be discovered and developed.

Sponsors:



International Conference on Planarization/CMP Technology

Organized by
VDE/VDI-Society Microelectronics,
Micro- and Precision Engineering (GMM)
German CMP User Group

in co-operation with
Japanese Planarization and CMP Technical Committee (JSPE)
Korea CMP User Group (KCOMPUG)
Northern California Chapter AVS (NCCAUS) CMPUG

Upon several requests towards increased co-operation of the local CMP users groups from Germany, Japan, Korea and the United States of America, the idea of a joint international CMP conference emerged in 2005. Following successful conferences in Tokyo, Japan (PacRim-CMP 2004), Seoul, Korea (PacRim-CMP 2005) and Foster City, California, USA (ICPT 2006), the International Conference on Planarization/CMP Technology ICPT 2007 in Dresden, Germany, is organized by the German CMP User Group within the German VDE/VDI-Society Microelectronics, Micro- and Precision Engineering. The mission of this conference is the provision of a forum for the worldwide CMP community for exchange and discussion on a high scientific level in order to support and advance the developments of this highly important field of semiconductor manufacturing.

Dr. Gerfried Zwicker
Fraunhofer Institute for
Silicon Technology (ISIT)
Conference Chairman



Subjects of Interest

- Copper/low-k CMP processes and control
- CMP process integration issues and reliability
- CMP defects
- CMP consumables (pads, slurries)
- CMP modelling, simulation and theory
- Metrology, characterization and test
- Advances in ECD/ECP/ECMP processes and tools
- CMP in emerging technologies
- Dielectric/STi CMP processes and control
- Corrosion control during CMP process
- Post CMP cleaning
- CMP equipment and metrology
- Chemical and physical mechanisms of CMP
- Advanced CMP process control techniques
- Low-shear CMP

Local Organization and Program Committee

Gerfried Zwicker, Conference Chairman (Fraunhofer Institute for Silicon Technology, Germany)
Johann W. Bartha (Dresden Technical University, Germany)
Katrin Blum (IHP, Germany)
Knut Gottfried (Fraunhofer IZM, Germany)
Karl Hensen (BASF AG, Germany)

Michael Kroell (Degussa, Germany)
Martin Kulawski (VTT, Finland)
Georg Moersch (Peter Wolters AG, Germany)
Uwe Stoeckgen (AMD, Germany)
Peter Thieme (Qimonda AG, Germany)
Dorit Wecker (Infineon Technologies AG, Germany)

Abstract

Those interested in actively participating in the conference and making oral/poster presentations are requested to submit a one page abstract in English to conference-papers@vde.com by June 8, 2007. The abstract should be a brief synopsis of your paper and should provide a quick outline of your presentation to judge the quality of your work. Please provide the full address of the corresponding author/presenter and indicate the preference of oral or poster presentation. The authors of accepted contributions will be notified by June 29, 2007.

Full Paper

It is planned to hand out a conference proceedings volume, printed and on CD-ROM, at the symposium. Therefore, authors of accepted papers are obliged to submit the full paper for publication in the proceedings. Deadline for manuscript submission is August 24, 2007. Detailed information about manuscript preparation will be given at notification.

Poster Session

In addition to the two-day symposium, a poster session will be held. The posters will be presented in a separate Poster session and will be showed during the entire conference.

Dresden City Tour

Dresden is famous for its historic down town, which has been widely restored after the destructions of world war II. Highlights are the rebuilt Frauenkirche (Notre Dame Church), the Semper Opera House, the baroque Zwinger (palace) and the recently re-opened Historical Green Vault in the Royal Palace with its famous treasury exhibition, to name only a few. For those interested in the cultural background of this year's ICPT host city, the organizers are preparing a Dresden City Tour on Saturday, October 27. More information can be found on the conference registration forms, which will be sent out in July.

Exhibition

The two-day tabletop exhibition is an integral part of the ICPT 2007 conference and takes place at an exhibition area close to the conference lecture room. Exhibition space of 4 m² or 6 m² (40 sqft or 60 sqft) with table, two chairs and poster board are available. Registration for the exhibition includes two full access badges, two copies of the proceedings and a company name listing in all promotional materials. For further information on the exhibition please contact Dr. Ronald Schnabel.



Contact

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